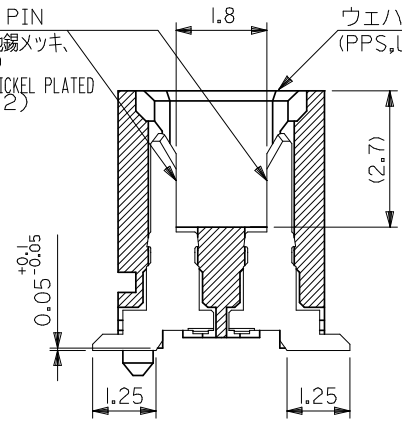


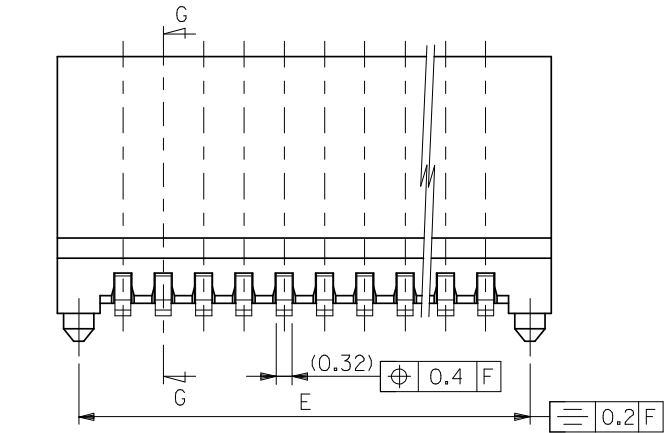
回路番号 1 (表示用切欠き)
CHAMFERING TO INDICATE CKT. NO.1

ピン PIN
(リン青銅、ニッケル下地銀メッキ、
 $t=0.32$)
(PHOS-BRO. TIN OVER NICKEL PLATED
 $t=0.32$)

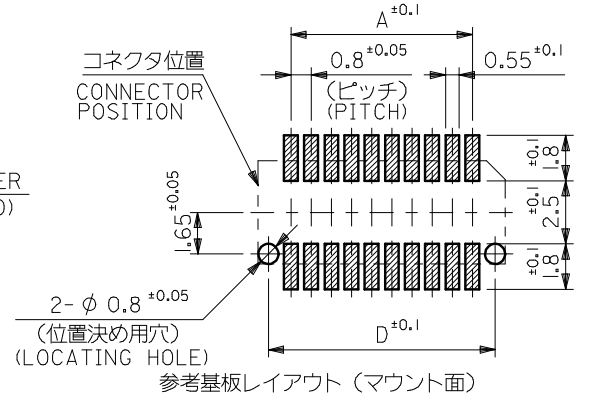
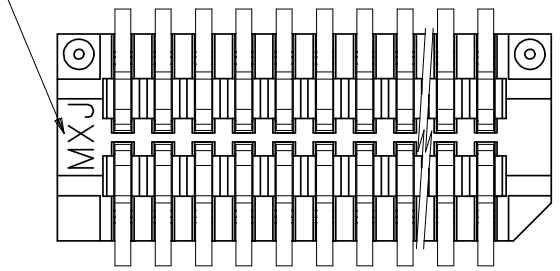
ウェハー WAFER
(PPS,UL94V-0)



SECT. G-G



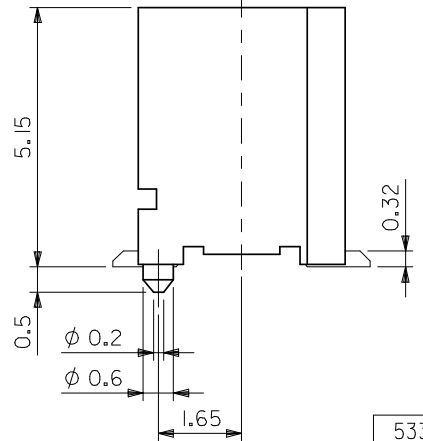
トレードマーク TRADE MARK



P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

注記 NOTES

1. 嵌合相手：52465 シリーズ
MATES WITH : 52465 SERIES
2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
3. 本製品は 53364-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**17



53364-**19
MODEL NO.

17.0	0.4	17.8	16.9	15.2	53364-4019	40
15.4	0.4	16.2	15.3	13.6	53364-3619	36
13.0	0.8	13.8	12.9	11.2	53364-3019	30
12.2	0.4	13.0	12.1	10.4	53364-2819	28
9.0	0.4	9.8	8.9	7.2	53364-2019	20
8.2	0.8	9.0	8.1	6.4	53364-1819	18
5.8	0.4	6.6	5.7	4.0	53364-1219	12
5.0	0.8	5.8	4.9	3.2	53364-1019	10
E	D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2008-3931 DRWN: MAKURAA 2008/05/26 CHKD: T. HARIYAMA 2008/05/26 APPR: NUKITA 2008/08/21	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NABEI		DATE		TITLE 0.8 BOARD TO BOARD CONN. WAFER ASS ST.SMT -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE		MOLEX INCORPORATED DOCUMENT NO. SD-53364-001 SHEET NO. 1 OF 1			
		30 OVER	±0.3	APPROVED BY M. SASAO		DATE					
A	REV	ANGULAR	±3 °	MATERIAL NO.		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									